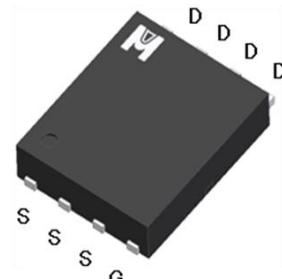
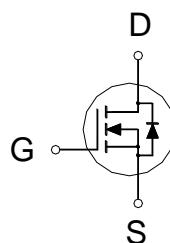


N-Channel Logic Level Enhancement Mode Field Effect Transistor

Product Summary:

BV_{DSS}	100V
$R_{DS(on)}$ (MAX.)	22mΩ
I_D	36A



UIS, Rg 100% Tested

RoHS & Halogen Free & TSCA Compliant



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_C = 25^\circ C$	I_D	36	A
	$T_C = 100^\circ C$		22	
Pulsed Drain Current ¹		I_{DM}	140	
Avalanche Current		I_{AS}	30	
Avalanche Energy	$L = 0.1mH, I_D=30A, R_G=25\Omega$	E_{AS}	45	mJ
Repetitive Avalanche Energy ²	$L = 0.05mH$	E_{AR}	22.5	
Power Dissipation	$T_C = 25^\circ C$	P_D	50	W
	$T_C = 100^\circ C$		20	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	°C

100% UIS testing in condition of $VD=50V$, $L=0.1mH$, $VG=10V$, $IL=18A$, Rated $VDS=100V$ N-CH

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	$R_{\theta JC}$		2.5	°C / W
Junction-to-Ambient	$R_{\theta JA}$		62	

¹Pulse width limited by maximum junction temperature.

²Duty cycle < 1%

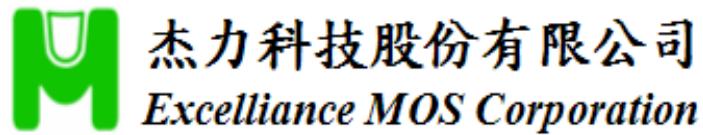
³The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz.

Copper, in a still air environment with $T_A = 25^\circ C$.

⁴Guarantee by Engineering test

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	100			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.0	2.0	3.0	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 80\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
		$V_{\text{DS}} = 70\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 125^\circ\text{C}$			25	
On-State Drain Current ¹	$I_{\text{D}(\text{ON})}$	$V_{\text{DS}} = 5\text{V}, V_{\text{GS}} = 10\text{V}$	36			A
Drain-Source On-State Resistance ¹	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 10\text{V}, I_D = 17\text{A}$		17	22	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 10\text{A}$		21	26	
Forward Transconductance ¹	g_{fs}	$V_{\text{DS}} = 5\text{V}, I_D = 17\text{A}$		32		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 50\text{V}, f = 1\text{MHz}$		1503		pF
Output Capacitance	C_{oss}			109		
Reverse Transfer Capacitance	C_{rss}			6		
Gate Resistance	R_g	$V_{\text{GS}} = 15\text{mV}, V_{\text{DS}} = 0\text{V}, f = 1\text{MHz}$		1.6		Ω
Total Gate Charge ^{1,2}	Q_g	$V_{\text{DS}} = 50\text{V}, V_{\text{GS}} = 10\text{V}, I_D = 17\text{A}$		21		nC
Gate-Source Charge ^{1,2}	Q_{gs}			10.5		
Gate-Drain Charge ^{1,2}	Q_{gd}			5.6		
Turn-On Delay Time ^{1,2}	$t_{\text{d}(\text{on})}$	$V_{\text{DS}} = 50\text{V}, I_D = 5\text{A}, V_{\text{GS}} = 10\text{V}, R_G = 6\Omega$		3.4		nS
Rise Time ^{1,2}	t_r			7		
Turn-Off Delay Time ^{1,2}	$t_{\text{d}(\text{off})}$			5		
Fall Time ^{1,2}	t_f			17		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_c = 25^\circ\text{C}$)						
Continuous Current	I_s				36	A
Pulsed Current ³	I_{SM}				140	
Forward Voltage ¹	V_{SD}	$I_F = 17\text{A}, V_{\text{GS}} = 0\text{V}$			1.3	V
Reverse Recovery Time	t_{rr}	$I_F = 17\text{A}, dI_F/dt = 500\text{A}/\mu\text{s}$		21		nS
Reverse Recovery Charge	Q_{rr}				92	nC



EMB22N10H

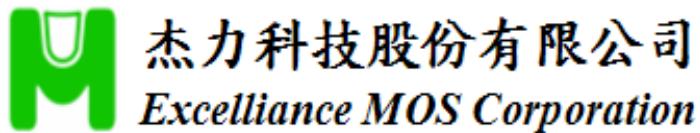
¹Pulse width limited by maximum junction temperature.

²Duty cycle < 1%

³The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz.

Copper, in a still air environment with $T_A = 25^\circ C$.

⁴Guarantee by Engineering test



EMB22N10H

Ordering & Marking Information:

Device Name: EMB22N10H for EDFN 5 x 6



B22N10: Device Name

ABCDEFG: Date Code

A: Assembly House

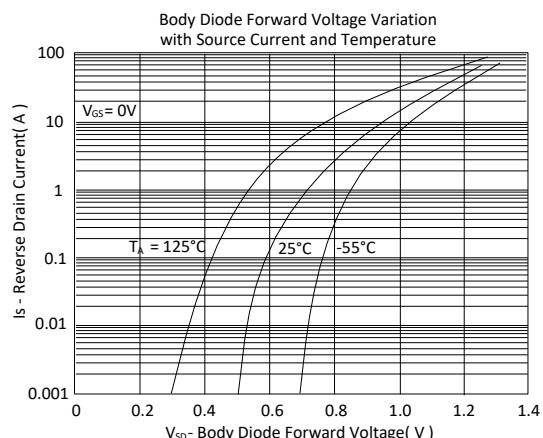
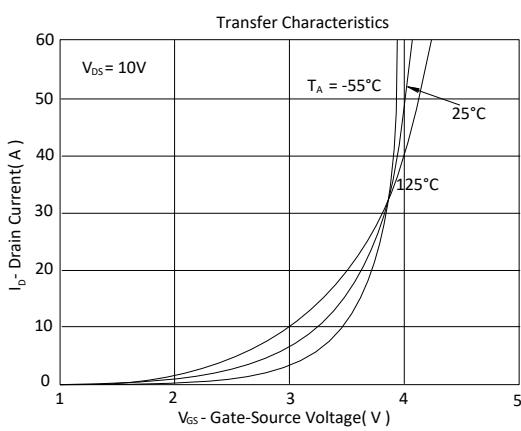
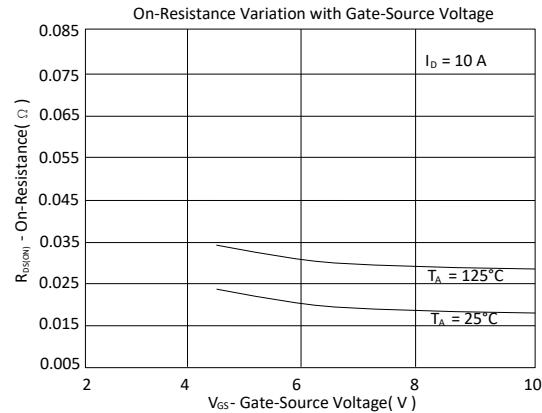
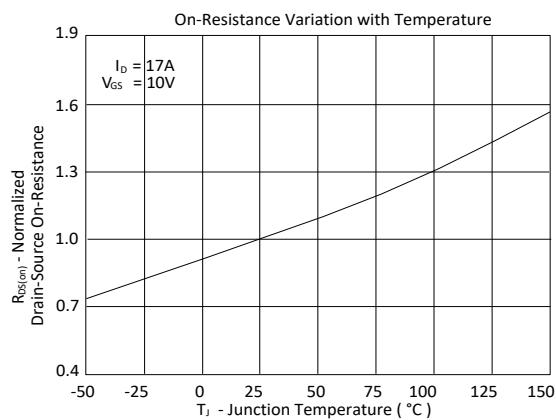
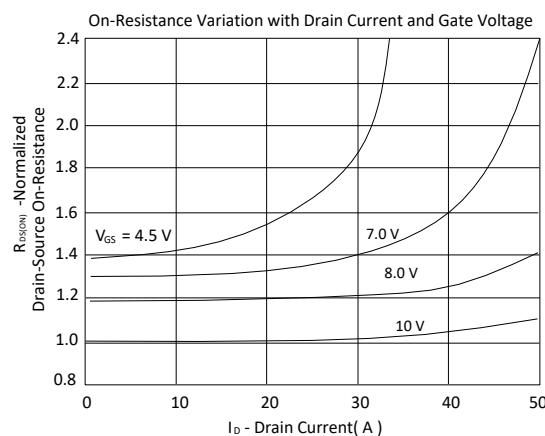
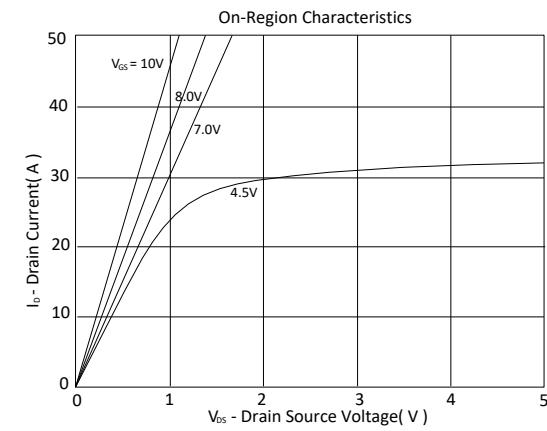
B: Year(A:2008 B:2009 C:2010....)

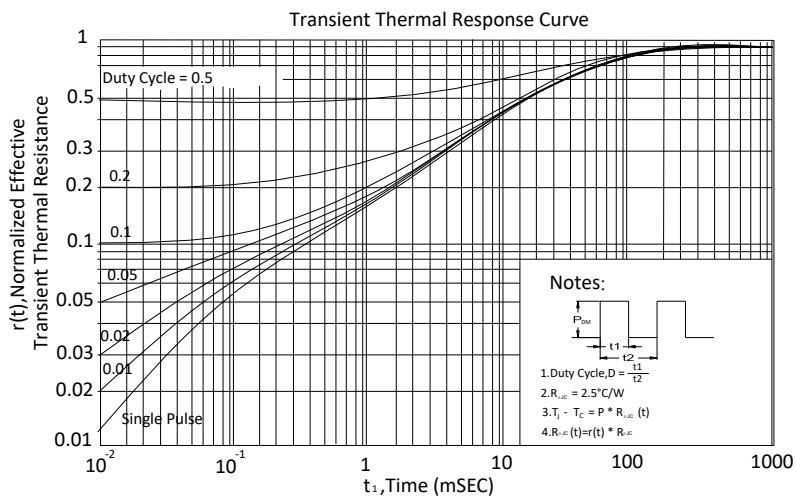
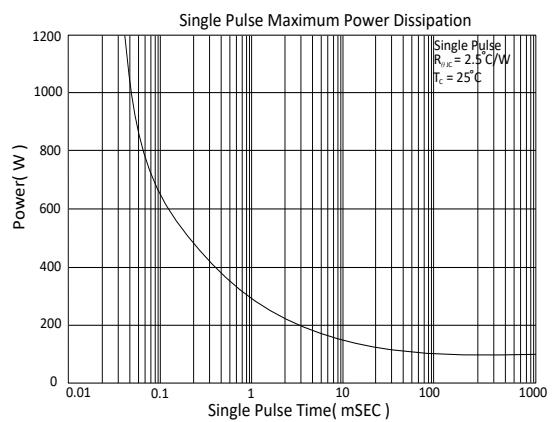
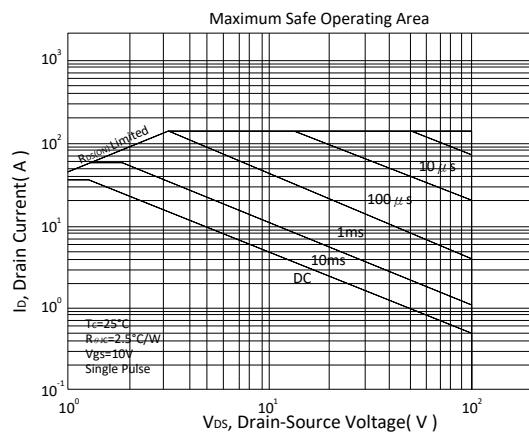
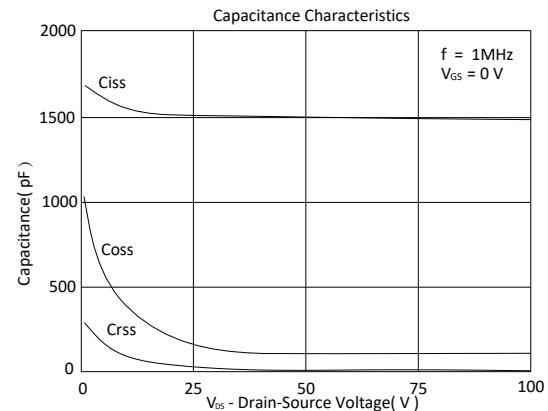
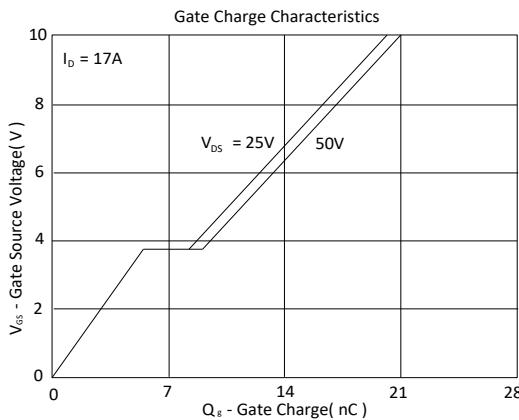
C: Month(A:01 B:02 C:03 D:04 E:05 F:06 G:07 H:08 I:09 J:10

K:11 L:12)

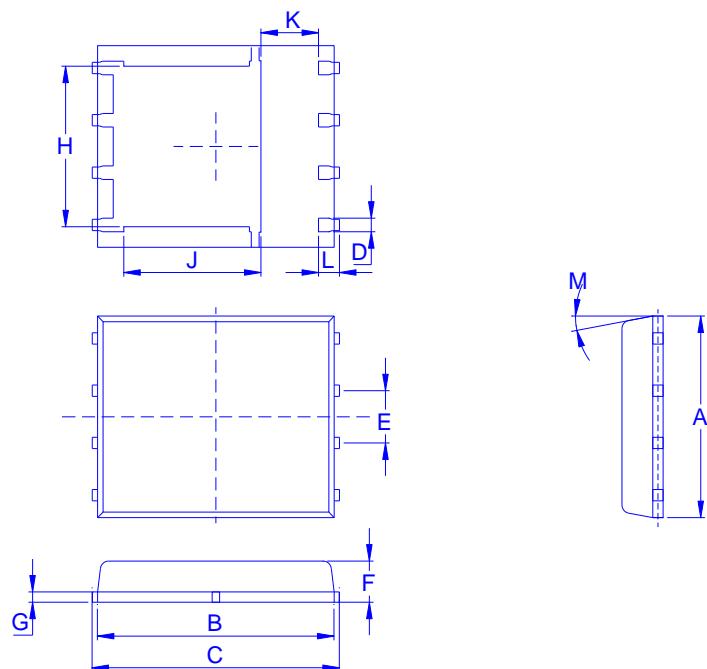
DEFG: Serial No.

TYPICAL CHARACTERISTICS





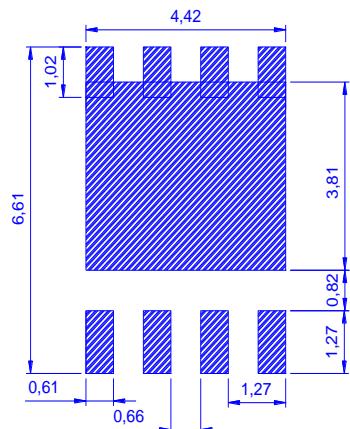
Outline Drawing



Dimension in mm

Dimension	A	B	C	D	E	F	G	H	J	K	L	M
Min	4.8	5.55	5.9	0.3	1.17	0.85	0.15	3.61	3.18	1	0.38	0°
Typ.	4.9	5.7	6	0.4	1.27	0.95	0.2	3.87	3.44	1.2	0.4	
Max	5.4	5.85	6.15	0.51	1.37	1.17	0.34	4.31	3.78	1.39	0.71	12°

Recommended minimum pads

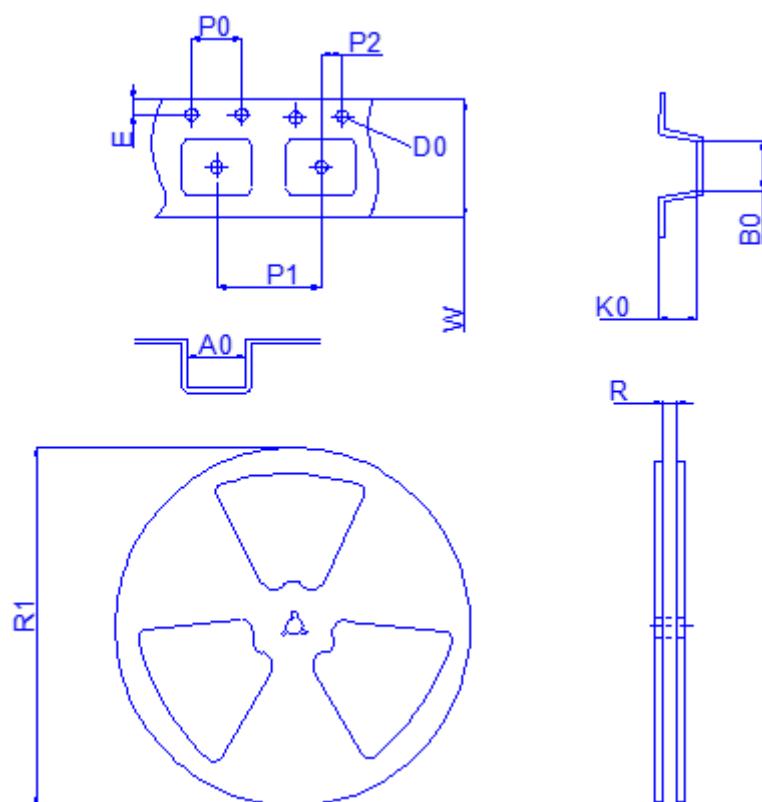




杰力科技股份有限公司
Excelliance MOS Corporation

EMB22N10H

Tape&Reel Information:2500pcs/Reel



Package	EDFN5X6
Reel	13"
Device orientation	FEED DIRECTION

Dimension in mm

Dimension	Carrier tape								Reel		
	A0	B0	D0	E	K0	P0	P1	P2	W	R	R1
Typ.	6.4	5.3	1.5	1.8	1.6	4	8	2	12	12.4	330
±	0.2	0.2	0.1	0.1	0.6	0.1	0.1	0.1	0.3	2	2